

HSB276AS

Silicon Schottky Barrier Diode for Balanced Mixer

REJ03G0594-0100

(Previous: ADE-208-838)

Rev.1.00 Apr 06, 2005

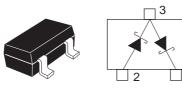
Features

- High forward current, Low capacitance.
- HSB276AS which is interconnected in series configuration is designed for balanced mixer use.
- CMPAK package is suitable for high density surface mounting and high speed assembly.

Ordering Information

Type No.	Laser Mark	Package Name	Package Code (Previous Code)
HSB276AS	E8	CMPAK	PTSP0003ZB-A
			(CMPAK)

Pin Arrangement



(Top View)

- 1. Cathode 2
- 2. Anode 1
- 3. Cathode 1 Anode 2

Absolute Maximum Ratings

 $(Ta = 25^{\circ}C)$

Item	Symbol	Value	Unit	
Repetitive peak reverse voltage	V_{RRM}	5	V	
Reverse voltage	V_R	3	V	
Average rectified current	lo *1	30	mA	
Junction temperature	Tj	125	°C	
Storage temperature	Tstg	−55 to +125	°C	

Note: 1. Per one device

Electrical Characteristics *1

 $(Ta = 25^{\circ}C)$

Symbol	Min	Тур	Max	Unit	Test Condition
/ _R	3	_	_	V	I _R = 1 mA
R	_	_	50	μΑ	V _R = 0.5 V
F	35	_	_	mA	$V_F = 0.5V$
0	_	_	0.90	pF	V _R = 0.5 V, f = 1 MHz
/C	_	_	0.10	pF	V _R = 0.5 V, f = 1 MHz
_	30		_	V	C = 200 pF, R = 0 Ω , Both forward and reverse direction 1 pulse.
/ F	R	3 3 5 5 C C —	3 — — — — — — — — — — — — — — — — — — —	3 — — 50 35 — — 0.90 C — 0.10	R 3 — V S — 50 μA 35 — mA — — 0.90 pF C — 0.10 pF

Notes: 1. Per one device

2. Failure criterion ; $I_R \geq 100~\mu A$ at V_R = 0.5 V

Main Characteristic

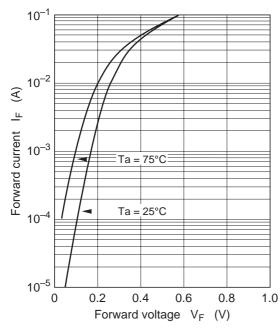


Fig.1 Forward current vs. Forward voltage

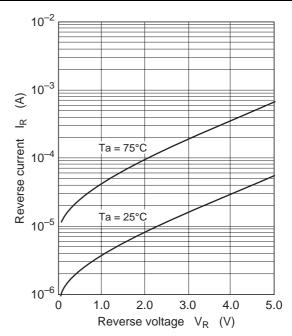


Fig.2 Reverse current vs. Reverse voltage

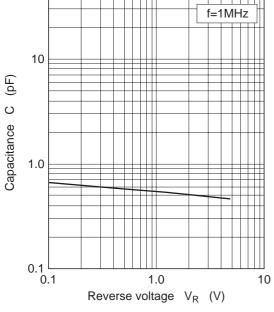
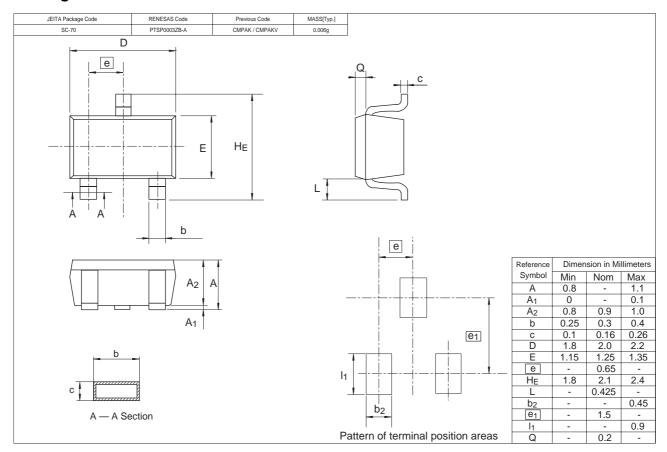


Fig.3 Capacitance vs. Reverse voltage

Package Dimensions



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- (ii) use of nontrammaple material of (iii) prevention against any maintention or misnap.

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